

## PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1  
Stylesheet Version v1.2

EPAS ID: PAT4764424

<b>SUBMISSION TYPE:</b>	NEW ASSIGNMENT
<b>NATURE OF CONVEYANCE:</b>	ASSIGNMENT
<b>CONVEYING PARTY DATA</b>	
<b>Name</b>	<b>Execution Date</b>
YEU-KUEN WEI	01/02/2018
SHU-YUN CHIEN	01/02/2018
SU-MEI CHEN WEI	01/02/2018
YI-CHE SU	01/02/2018
<b>RECEIVING PARTY DATA</b>	
<b>Name:</b>	INDUSTRIAL TECHNOLOGY RESEARCH INSTITUTE
<b>Street Address:</b>	NO. 195, SEC. 4, CHUNG HSING RD., CHUTUNG
<b>City:</b>	HSINCHU
<b>State/Country:</b>	TAIWAN
<b>Postal Code:</b>	31040
<b>PROPERTY NUMBERS Total: 1</b>	
<b>Property Type</b>	<b>Number</b>
<b>Application Number:</b>	15856475
<b>CORRESPONDENCE DATA</b>	
<b>Fax Number:</b>	(703)205-8050
<i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.</i>	
<b>Phone:</b>	703-205-8000
<b>Email:</b>	Derya.Sevinc@bskb.com, mailroom@bskb.com
<b>Correspondent Name:</b>	BIRCH STEWART KOLASCH & BIRCH, LLP
<b>Address Line 1:</b>	8110 GATEHOUSE ROAD, SUITE 100E
<b>Address Line 4:</b>	FALLS CHURCH, VIRGINIA 22042-0747
<b>ATTORNEY DOCKET NUMBER:</b>	0941-3735PUS1
<b>NAME OF SUBMITTER:</b>	DERYA SEVINC
<b>SIGNATURE:</b>	/Derya Sevinc/
<b>DATE SIGNED:</b>	01/08/2018
<b>Total Attachments: 2</b>	
source=2018-1-4_Assignmentasfiled_0941-3735PUS1#page1.tif	
source=2018-1-4_Assignmentasfiled_0941-3735PUS1#page2.tif	

**ASSIGNMENT**

WHEREAS, YEU-KUEN WEI, Shu-Yun CHIEN, Su-Mei Chen WEI and Yi-Che SU hereafter referred to as ASSIGNOR, has/have invented certain new and useful improvements as described and set forth in the below identified application for United States Letters Patent:

Title: Aqueous coating material and method for manufacturing the same

Filed: 28-Dec-2017 Serial No. 15/856,475

Executed on: January 2, 2018

WHEREAS, Industrial Technology Research Institute of No. 195, Sec. 4, Chung Hsing Rd., Chung, Hsinchu 31040, Taiwan, R. O. C. hereinafter referred to as ASSIGNEE, is desirous of acquiring ASSIGNOR'S interest in the said invention and application and in any U.S. Letters Patent which may be granted on the same;

NOW, THEREFORE, TO ALL WHOM IT MAY CONCERN: Be it known that, for good and valuable consideration, receipt of which is hereby acknowledged by Assignor, Assignor has/have sold, assigned and transferred, and by these presents does/do sell, assign and transfer unto the said Assignee, and Assignee's successors and assigns, all his/her/their rights, title and interest in and to the said invention and application and all future improvements thereon, and in and to any Letters Patent which may hereafter be granted on the same in the United States, the said interest to be held and enjoyed by said Assignee as fully and exclusively as it would have been held and enjoyed by said Assignor had this Assignment and transfer not been made, to the full end and term of any Letters Patent which may be granted thereon, or of any division, renewal, continuation in whole or in part, substitution, conversion, reissue, prolongation or extension thereof.

Assignor further agrees/agree that he/she/they will, without charge to said Assignee, but at Assignee's expense, cooperate with Assignee in the prosecution of said application and/or applications, execute, verify, acknowledge and deliver all such further papers, including applications for Letters Patent and for the reissue thereof, and instruments of assignment and transfer thereof, and will perform such other acts as Assignee lawfully may request, to obtain or maintain Letters Patent for said invention and improvement, and to vest title thereto in said Assignee, or Assignee's successors and assigns.

IN TESTIMONY WHEREOF, Assignor has/have signed his/her/their name(s) on the date(s) indicated.

<b>Full name of sole or first inventor: YEU-KUEN WEI</b>	
Inventor's signature: <i>Yeu-Kuen Wei</i>	Date: <i>2018 / 1 / 2</i>

<b>Full name of second inventor: Shu-Yun CHIEN</b>	
Inventor's signature: <i>Shu-Yun Chien</i>	Date: <i>2018 / 1 / 2</i>

<b>Full name of third inventor:</b> Su-Mei Chen WEI	
Inventor's signature: Su-Mei Chen Wei	Date: 2018/1/2

<b>Full name of fourth inventor:</b> Yi-Che SU	
Inventor's signature: Yi-Che SU	Date: 2018/1/2